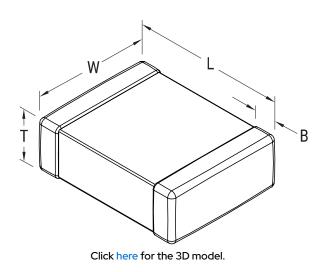




CBR-SMD RF COG, Ceramic, 2.3 pF, +/-0.25 pF, 50 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0805



General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	12.03 mg
Notes	Solder Wave or Solder Reflow.
Shelf Life	78 Weeks
MSL	1

2.3 pF +/-0.25 pF

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	0.85mm +/-0.1mm
В	0.5mm +/-0.2mm

W	1.25mm +/-0.2mm	Voltage DC	50 VDC
Т	0.85mm +/-0.1mm	Dielectric Withstanding Voltage	125 VDC
В	0.5mm +/-0.2mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.224%
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Hour
Packaging Quantity	4000	Insulation Resistance	10 GOhms

W	1.25mm +/-0.2mm	Voltage DC	50 VDC
Т	0.85mm +/-0.1mm	Dielectric Withstanding Voltage	125 VDC
В	0.5mm +/-0.2mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.224%
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Hour
Packaging Quantity 4000	Insulation Resistance	10 GOhms	
		Quality Factor	446

Specifications Capacitance

Tolerance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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